

## 1. General description

Standard reverse recovery power diode in a TO247-2L package.

## 2. Features and benefits

- Low forward voltage drop
- Low leakage current
- High voltage capability
- High inrush current capability

## 3. Applications

- Input rectifier
- Bypass diode

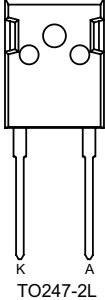
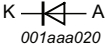
## 4. Quick reference data

Table 1. Quick reference data

| Symbol                         | Parameter                           | Conditions   | Values |     |      |      | Unit |
|--------------------------------|-------------------------------------|--|--------|-----|------|------|------|
| <b>Absolute maximum rating</b> |                                     |  |        |     |      |      |      |
| $V_{RRM}$                      | repetitive peak reverse voltage     |  | 2000   |     |      |      | V    |
| $I_{F(AV)}$                    | average forward current             | $\delta = 0.5$ ; square-wave pulse; $T_{mb} \leq 130$ °C; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a> | 60     |     |      |      | A    |
| $I_{FSM}$                      | non-repetitive peak forward current | $t_p = 10$ ms; $T_{j(init)} = 25$ °C; sine-wave pulse; <a href="#">Fig. 4</a>  | 950    |     |      |      | A    |
|                                |                                     | $t_p = 8.3$ ms; $T_{j(init)} = 25$ °C; sine-wave pulse   | 1045   |     |      |      | A    |
| Symbol                         | Parameter                           | Conditions   | Notes  | Min | Typ  | Max  | Unit |
| <b>Static characteristics</b>  |                                     |  |        |     |      |      |      |
| $V_F$                          | forward voltage                     | $I_F = 60$ A; $T_j = 25$ °C; <a href="#">Fig. 6</a>  |        | -   | 1.07 | 1.12 | V    |
|                                |                                     | $I_F = 60$ A; $T_j = 150$ °C; <a href="#">Fig. 6</a>   |        | -   | 0.99 | 1.05 | V    |

## 5. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description                        | Simplified outline  | Graphic symbol  |
|-----|--------|------------------------------------|---|---|
| 1   | K      | cathode                            |  <p style="text-align: center;">TO247-2L</p> |  |
| 2   | A      | anode                              |   |   |
| mb  | mb     | mounting base; connected to cathod |   |   |

## 6. Ordering information

Table 3. Ordering information

| Type number | Package Name | Orderable part number | Packing method | Small packing quantity | Package version | Package issue date |
|-------------|--------------|-----------------------|----------------|------------------------|-----------------|--------------------|
| WND60P20W   | TO247-2L     | WND60P20WQ            | Tube           | 30                     | TO247L-2L       | 12-Nov-2020        |

## 7. Marking

Table 4. Marking codes

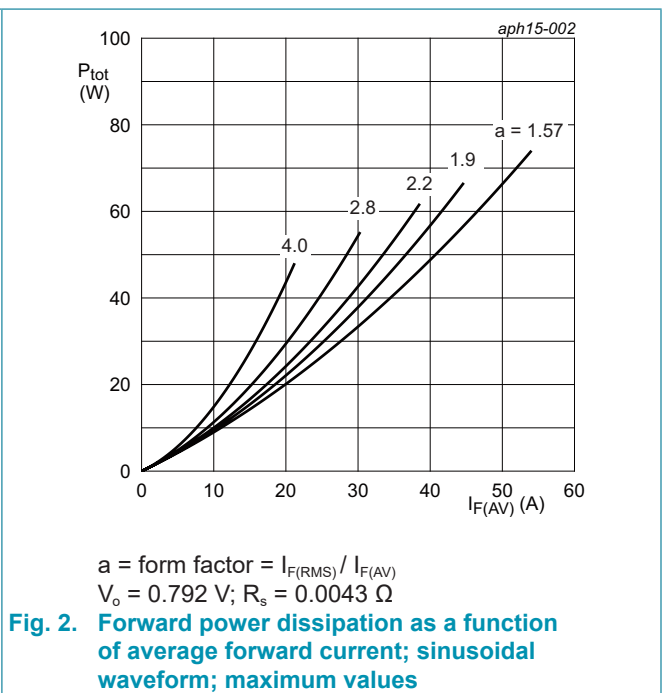
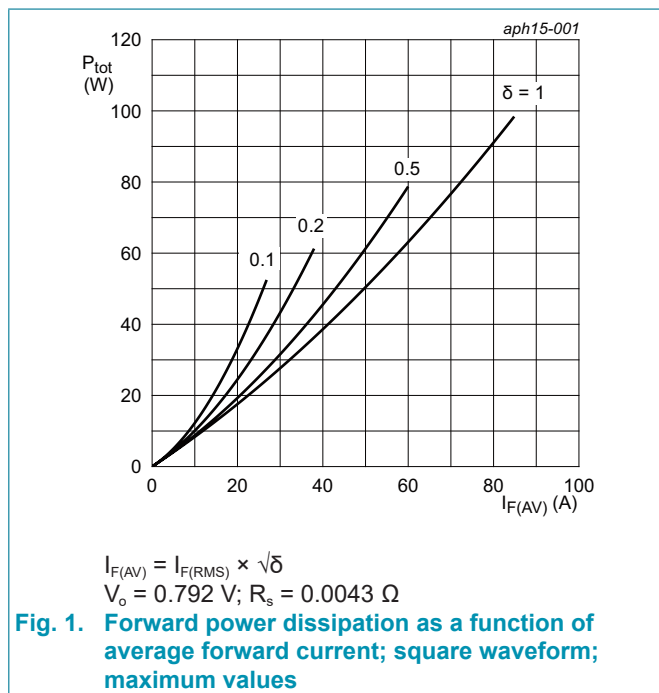
| Type number | Marking codes                |
|-------------|------------------------------|
| WND60P20W   | D60P20<br>2000<br>PJLxxxx xx |

## 8. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol      | Parameter                           | Conditions  | Values     | Unit                 |
|-------------|-------------------------------------|---|------------|----------------------|
| $V_{RRM}$   | repetitive peak reverse voltage     |   | 2000       | V                    |
| $V_{RWM}$   | crest working reverse voltage       |   | 2000       | V                    |
| $V_R$       | reverse voltage                     | DC  | 2000       | V                    |
| $I_{F(AV)}$ | average forward current             | $\delta = 0.5$ ; square-wave pulse; $T_{mb} \leq 130\text{ }^\circ\text{C}$ ;<br><a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a> | 60         | A                    |
| $I_{FSM}$   | non-repetitive peak forward current | $t_p = 10\text{ ms}$ ; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$ ; sine-wave pulse;<br><a href="#">Fig. 4</a>                                       | 950        | A                    |
|             |                                     | $t_p = 8.3\text{ ms}$ ; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$ ; sine-wave pulse   | 1045       | A                    |
| $I^2t$      | $I^2t$ for fusing                   | SIN; $t_p = 10\text{ ms}$   | 4513       | $\text{A}^2\text{s}$ |
| $T_{stg}$   | storage temperature                 |   | -55 to 150 | $^\circ\text{C}$     |
| $T_j$       | junction temperature                |   | 150        | $^\circ\text{C}$     |



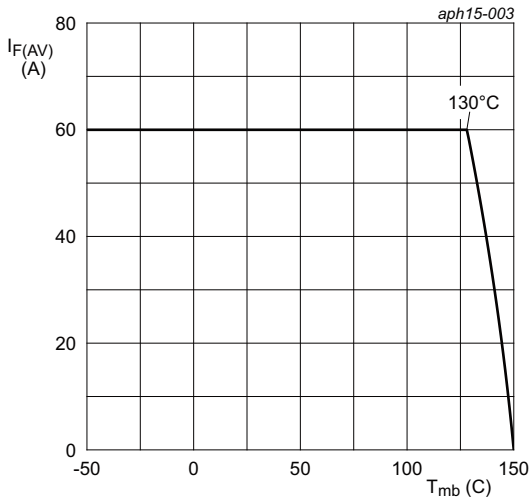


Fig. 3. Forward current as a function of mounting base temperature; maximum values

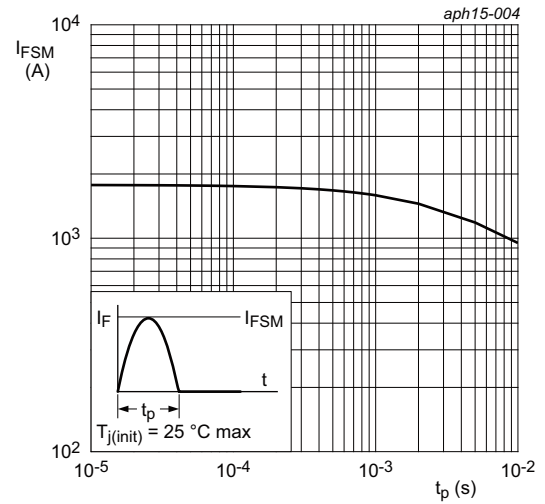


Fig. 4. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values

### 9. Thermal characteristics

Table 6. Thermal characteristics

| Symbol         | Parameter  | Conditions             | Notes | Min | Typ | Max  | Unit |
|----------------|--|------------------------|-------|-----|-----|------|------|
| $R_{th(j-mb)}$ | thermal resistance from junction to mounting base    | <a href="#">Fig. 5</a> |       | -   | -   | 0.25 | K/W  |
| $R_{th(j-a)}$  | thermal resistance from junction to ambient free air | in free air            |       | -   | 40  | -    | K/W  |

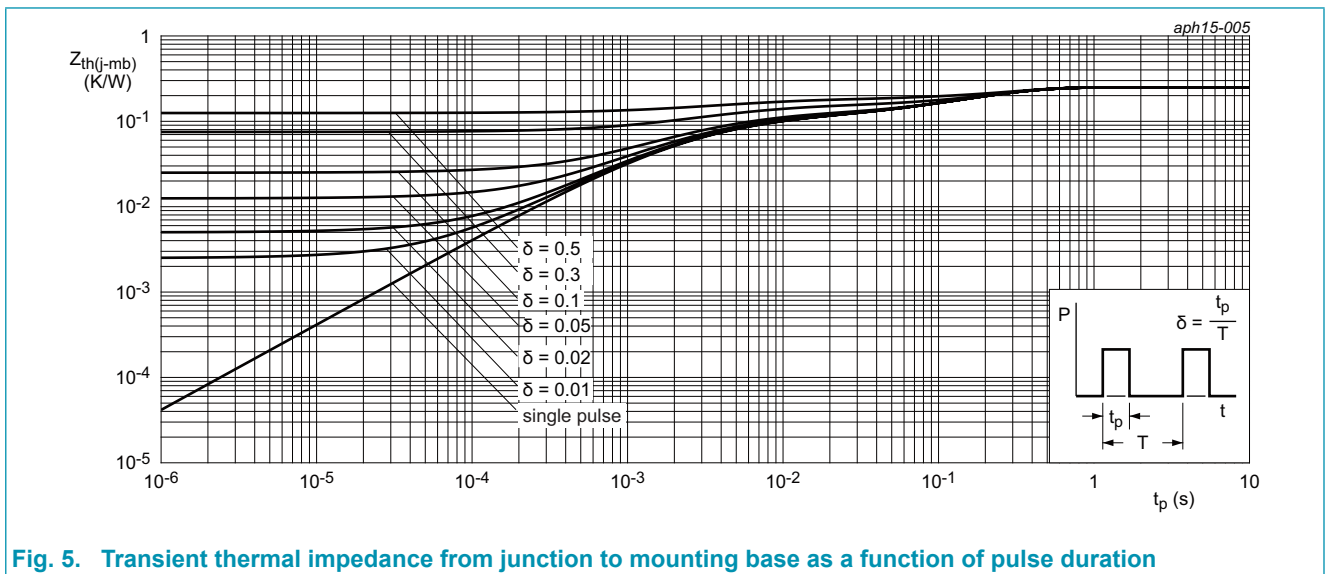
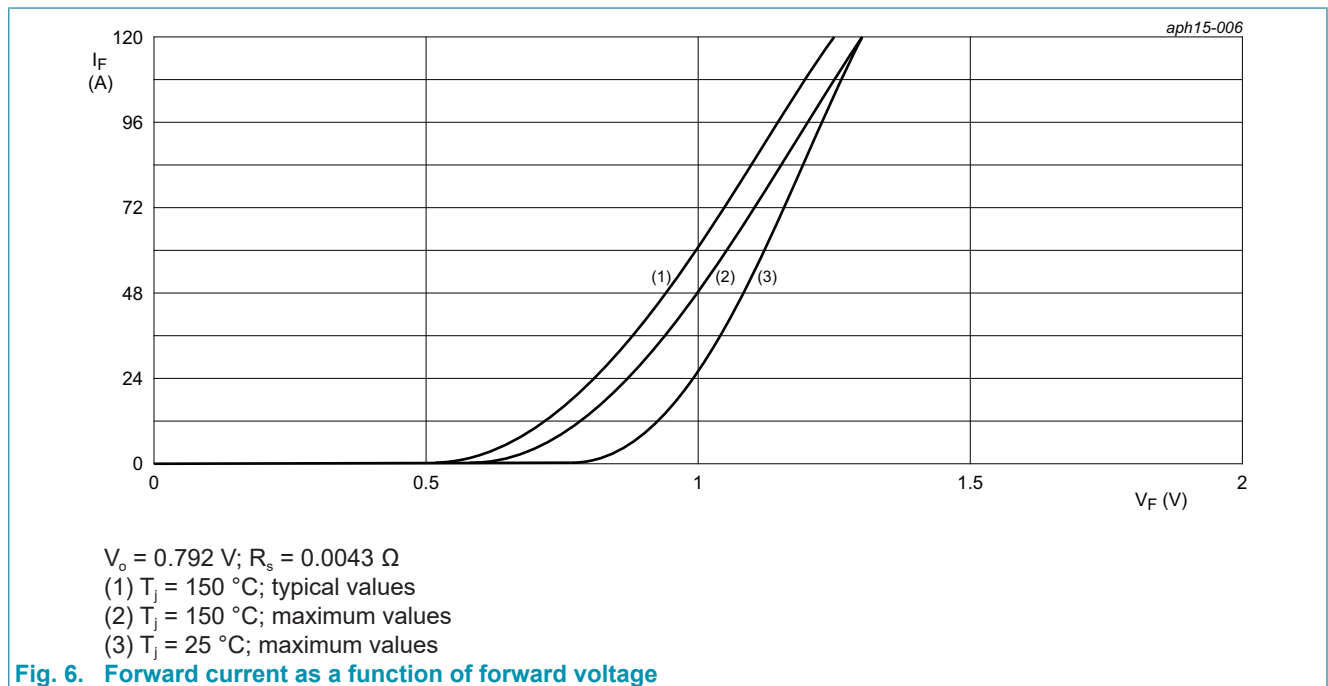


Fig. 5. Transient thermal impedance from junction to mounting base as a function of pulse duration

## 10. Characteristics

Table 7. Characteristics

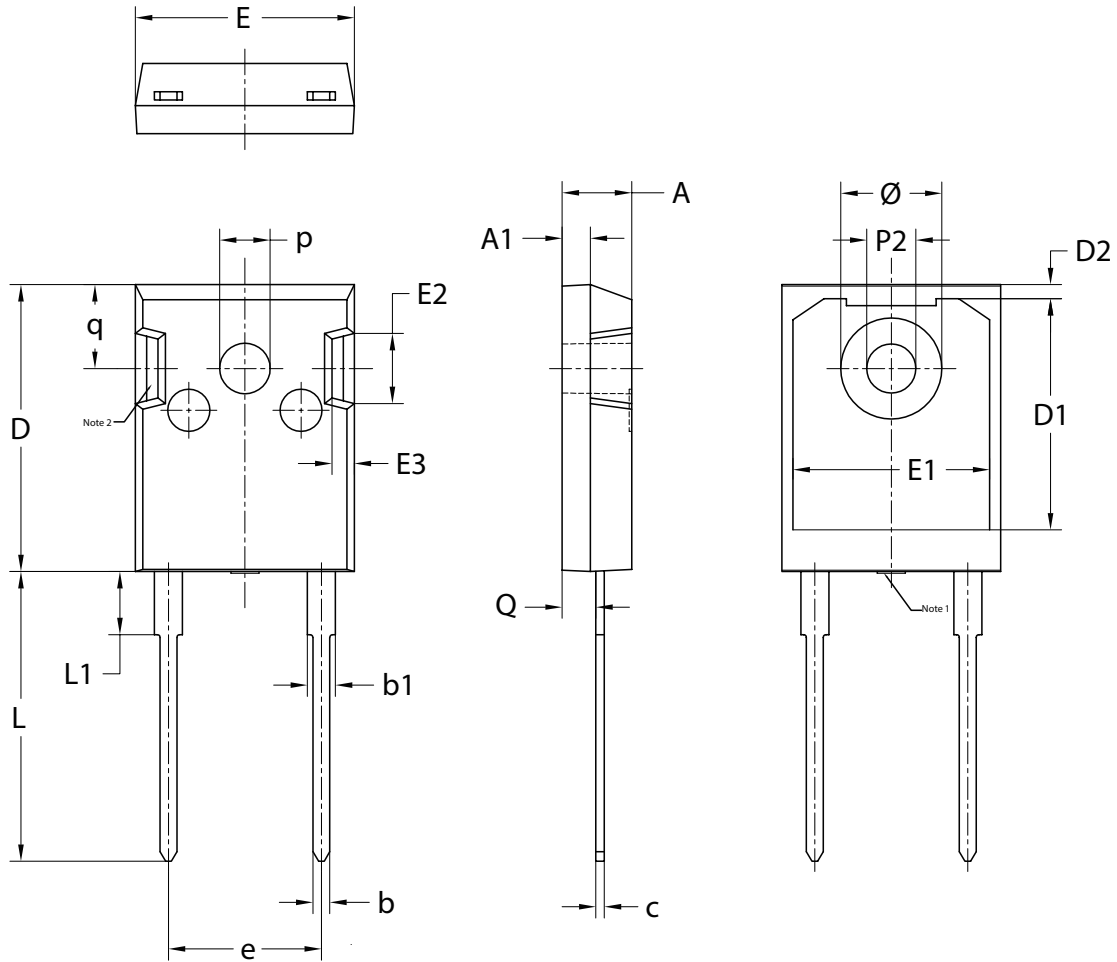
| Symbol                        | Parameter       | Conditions  | Notes | Min | Typ  | Max  | Unit          |
|-------------------------------|-----------------|---|-------|-----|------|------|---------------|
| <b>Static characteristics</b> |                 |   |       |     |      |      |               |
| $V_F$                         | forward current | $I_F = 60\text{ A}; T_j = 25\text{ °C}; \text{Fig. 6}$  |       | -   | 1.07 | 1.12 | V             |
|                               |                 | $I_F = 60\text{ A}; T_j = 150\text{ °C}; \text{Fig. 6}$ |       | -   | 0.99 | 1.05 | V             |
| $I_R$                         | reverse current | $V_R = 2000\text{ V}; T_j = 25\text{ °C}$               |       | -   | -    | 50   | $\mu\text{A}$ |
|                               |                 | $V_R = 2000\text{ V}; T_j = 150\text{ °C}$              |       | -   | -    | 1.5  | mA            |



### 11. Package outline

Plastic single-ended through-hole package; heatsink mounted; 1 mounting hole; 2 leads TO-247

TO247-2L



| UNIT | A    | A <sub>1</sub> | b    | b <sub>1</sub> | c    | D     | D <sub>1</sub><br>⊕ | D <sub>2</sub> | E     | E <sub>1</sub> | E <sub>2</sub> | E <sub>3</sub> | e     | L     | L <sub>1</sub> | P <sub>2</sub> | p    | Q    | q    | Ø    |
|------|------|----------------|------|----------------|------|-------|---------------------|----------------|-------|----------------|----------------|----------------|-------|-------|----------------|----------------|------|------|------|------|
| mm   | 5.20 | 2.10           | 1.40 | 2.20           | 0.70 | 20.60 | 16.20               | 1.20           | 15.75 | 14.22          | 5.20           | 1.80           | 10.90 | 20.72 | 4.75           | 3.60           | 3.70 | 2.60 | 6.18 | 7.30 |
|      | 4.70 | 1.90           | 1.00 | 1.80           | 0.50 | 20.30 | 16.87               | 0.80           | 15.45 | 13.82          | 4.80           | 1.40           | BSC   | 20.22 | 4.25           | 3.40           | 3.50 | 2.20 | 5.78 | 7.10 |

Note:

1. Mold resin protrusion max 0.127mm.
2. Metal exposed with Sn plating.

## 12. Legal information

### Data sheet status

| Document status [1][2]         | Product status [3] | Definition  |
|--------------------------------|--------------------|---|
| Objective [short] data sheet   | Development        | This document contains data from the objective specification for product development. |
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- [2] The term 'short data sheet' is explained in section "Definitions".
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